

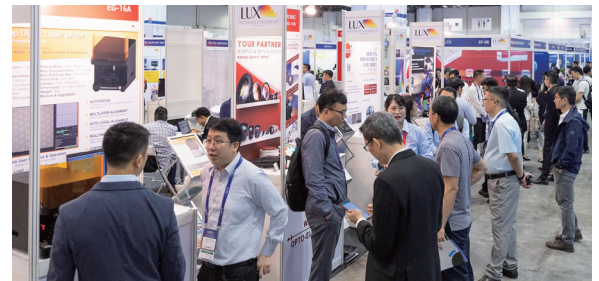
APPLICATION OF PHOTONICS TECHNOLOGY IN THE **OPTICAL COMMUNICATION** INDUSTRY

Asia Photonics Expo (APE), a world's leading comprehensive photonics platform, will be held at the Sands Expo and Convention Centre in Singapore from 26 to 28 February 2025. It focuses on cutting-edge technologies and emerging markets in the fields of optical communication, optics, laser, infrared, sensing, and display, including **optical communication chips, components and modules, optical communication wiring products, optical fiber cables, semiconductor materials, semiconductor equipment, testing and measurement instruments**. It serves as a one-stop platform for professionals in the optical communication industry to seek upstream and downstream products, innovative technologies, engage in trade negotiations, and facilitate procurement.

Exhibit Profile

Core Components: Optical fiber materials, optical fiber cable / fiber sensing, wiring products and cables, semiconductor materials, optical communication chips, optical communication devices/modules.

Production and Manufacturing: Semiconductor equipment, optical communication transmission equipment, testing and measurement instrument.

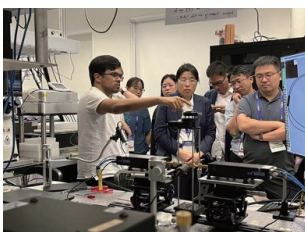


CONCURRENT ACTIVITIES



Gala Dinner

Over 120 top-level executives of our exhibitors and partners attended the gala dinner and took the opportunity to engage in high-level discussions, exchange ideas, and explore potential collaborations.



Site Tour

APE co-organized with Singapore University of Technology and Design and LUX Photonics Consortium to curate a site tour which attracted over 40 companies to join, aiming to link between academia and industry.



Happy Hours

It will be held at VIP lounge to facilitate the networking and collaboration between exhibitors and VIP visitors.

CONCURRENT CONFERENCES

Industry Forum

Explore the cutting-edge optoelectronic technology and gain in-depth insights into its latest developments across various photonics application fields, thereby driving innovation in upstream and downstream products.

2024 Programmes:

- Yole Group Photonics Integration Forum: Transforming Data Communication Applications
- Next-Generation Data Center Optical Interconnect Technology Evolution Forum



BOOTH APPLICATION



APE AT A GLANCE

*Only part of exhibits, listed in no order.

Optical Chip

Active Component Chip

- Laser Chip**
 - VCSEL Chip
 - DWL Chip
 - EML Chip
 - EEL Chip
 - Silicon Optical Chip
 - Thin-Film Lithium Niobate Modulation Chip
- Detector Chip**
 - PIN Chip
 - APD Chip
- Amplifier Chip**
 - LA Chip
 - TIA Chip
 - LD Driver Chip

Passive Component Chip

- PLC Chip
- WDM Chip
- Optical Switch Chip
- Optical Attenuator Chip

Optical Subassembly

- Ceramic Ferrule
- Ceramic Insert
- Ceramic Heat Sink
- Micro-Optical Component
- Metalized Optical Fiber Assembly
- Optical Window Cover and Heat Sink Component
- Optical Isolator
- Optoelectronic Hybrid Connector
- Fiber Optic Quick Connector
- Fiber Optic Splitter
- Fiber Optic Adapter
- Pluggable Optical Interconnect Assembly
- Large-Area Photodetector Assembly

Optical Component

Active Optical Component

- Light Source/Laser
 - VCSEL
 - Semiconductor Light-Emitting Diode
 - Laser Diode
 - Narrow Linewidth Tunable Laser
 - Butterfly Laser
 - DFB Laser
 - EML Laser
- Optical Amplifier**
 - Semiconductor Optical Amplifier
 - Fiber Amplifier
- Optical Detectors**
 - PIN Photodetector
 - APD Photodetector
- Others**
 - High-Speed LCOS Spatial Light Modulator
 - Electro-absorption Modulated Transmitter
 - Thin-Film Lithium Niobate Modulator
 - TOSA
 - ROSA
 - BOSA

Passive Optical Component

- Optical Fiber Connector
- PLC Splitter
- Optical Switch
- Optical Isolator
- Wavelength Division Multiplexer/Demultiplexer (WDM/DWD)
- Optical Attenuator (FOA/VOA)

Optical Fiber Material

- Optical Fiber Preform
- Optical Fiber Coating Material
- Aligned Aramid Yarn
- Optical Fiber Polishing Fluid
- Optical Fiber Polishing Powder
- Optical Fiber Protective Sleeve
- Heat-Shrinkable Connector
- Heat-Shrinkable Mid-Span Joint
- Heat-Shrinkable Mid-Span Sleeve
- Heat-Shrinkable Cap
- Mini Cap
- Night-core Fiber
- Heat-Shrinkable Tubing

Optical Fiber/Cable

- Single-Mode Optical Fiber
- Multi-Mode Optical Fiber
- Plastic Optical Fiber
- Glass Optical Fiber
- Quartz Optical Fiber
- Fibrium-Doped Optical Fiber
- Ytterbium-Doped Optical Fiber
- Photoelectric Composite Cable
- Outdoor Optical Cable
- Figure-8 Optical Cable
- Data Center Optical Cable
- Miniature Distribution Optical Cable
- Multi-Core Bundled Soft Optical Cable
- Underwater Submarine Optical Cable

Optical Module

- High-Speed Optical Module
- 400G Optical Module
- 800G Optical Module
- 100G Optical Module
- Coherent Optical Module
- Ultra-wide Passband thermal AWG Module
- Full Range of Optical Module
- 100G Series and 25G Series Optical Module
- Pluggable Optical Module
- 50G Front-Haul Optical Module

Optical Transmission Equipment

- S-Photronics Aligner
- All-Optical Switch
- PDH Terminal Equipment
- WDM Equipment
- Optical Transmission Equipment
- Optical Connection Equipment
- OLT Access Equipment
- Aggregation and Distribution Equipment
- Optical Pulse Analyzer
- Optical Amplification/Protection Subsystem
- DWDM Open Access System
- High-Integration WDM Transmission System
- Optical Cable Automatic Monitoring and Management System
- High-Performance Optical Power Meter

Data Center Equipment

- Ethernet Switch
- Layer 3 Network Switch
- Optical Access Terminal
- Data Center Switch
- Network/Server Cabinet
- Core Aggregation Switch
- Integrated Intelligent Cabinet
- Micro-Modular Data Center

Wire and Cable

- Active Cable
- High-Speed Cable
- Network Cable
- Copper Cable
- Straight Copper Cable
- Coaxial Cable
- Network Patch Cable
- Polyurethane Cable Jacket

Instrument

- Optical Network Tester
- Communication Testing Instrument
- High-Performance Spectrometer
- High-Performance Bit Error Rate Tester (BERT)
- Ethernet Tester
- Oscilloscope
- Rapid Scanning Test System
- Wavelength Scanning Test System
- Optoelectronic Network Analyzer
- Signal Quality Analyzer
- Fiber Fusion Splicer

Cable Production Equipment

- Numerical control quartz tube and rod shaping grinder
- Patch Cord Production Equipment
- Automatic Fiber Double Drum Winder
- Fiber Coil Winding Machine
- Optical Fiber Grinding Equipment
- Wire Winding and Tying Machine
- Fully Automatic Labeling Machine
- Tensile and Compression Testing Machine
- High-Speed Coloring Machine
- Cable Jacket Extrusion Machine
- Copper Wire Twisting Machine
- Wire Cutting Machine
- Fully Automatic Receptacle Assembly Machine
- Fully Automatic Winding and Twisting Hanging Cutting Cable Machine

Production & Manufacturing

Semiconductor Material / Equipment and Manufacturing

Materials

- Indium Phosphide
- Gallium Nitride
- Gallium Arsenide
- Monocrystalline Silicon
- Organic Germanium
- Germanium Wafer
- Gallium Aluminum Arsenide
- Epitaxial Wafer
- Photomask
- Lithium Niobate Single-Crystal Thin Film
- Passive Component
- Silicon Photonics
- Adhesives

Equipment and Manufacturing

- Chip Epitaxial Equipment
- Chip Cleaning Machine
- Chip Tester
- Pick-and-Place Machine
- Cleaning Machine
- Slicing Machine
- Semiconductor Packaging and Testing
- LD Automatic Eutectic Bonder
- PD Automatic Eutectic Bonder
- Automatic Wire Bonder
- Optical Wire Bonding Machine
- Centrifugal Debubbling Machine
- Automatic Optical Path Alignment Machine
- Optical Coupling Glue Dispenser
- Wafer Cutter
- Wafer Testing System
- High-Precision Die Bonder
- Coating Equipment
- Vacuum Drying Oven
- Parallel Sealing Machine
- Helium Mass Spectrometer Leak Detector



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APE 2024 POST SHOW REPORT